Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	2 X 3 X 0.75 (1.7 X 1.55EP)
Lead Count	4
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	7.72E-03	86.2	862000	33.39	333928
Thermosets	Epoxy resin	Proprietary	5.38E-04	6.0	60000	2.32	23243
Thermosets	Phenol resin	Proprietary	5.38E-04	6.0	60000	2.32	23243
Other inorganic materials	Metal Hydroxide	Proprietary	1.34E-04	1.5	15000	0.58	5811
Other inorganic materials	Carbon black	1333-86-4	2.69E-05	0.3	3000	0.12	1162
Subtotal			8.96 E-03	100.00	1000000	38.74	387387

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.00 E-02	97.50	975000	43.22	432180
Copper & its alloys	Iron	7439-89-6	2.41 E-04	2.35	23500	1.04	10417
Copper & its alloys	Zinc	7440-66-6	1.23 E-05	0.12	1200	0.05	532
Copper & its alloys	Phosphorus	7723-14-0	3.08 E-06	0.03	300	0.01	133
Subtotal			1.03 E-02	100.00	1000000	44.33	443262

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	6.89 E-04	100.0	1000000	2.98	29803

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	4.20 E-04	100.0	1000000	1.82	18159

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.74 E-04	100.0	1000000	0.75	7529

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.51 E-03	100.0	1000000	10.83	108330

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Epoxy Resin	Proprietary	8.44 E-05	66.00	660000	0.36	3650
Others	Polymeric Resin	Proprietary	4.35 E-05	34.00	340000	0.19	1880
Subtotal			1.28 E-04	100.0	1000000	0.55	5530

	Weight (g)	Percentage (%)	PPM
Package Totals	**2.31 E-02**	100	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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